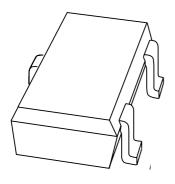
DISCRETE SEMICONDUCTORS

DATA SHEET



BF820WNPN high-voltage transistor

Product specification Supersedes data of 1997 Sep 03 2003 Sep 09





NPN high-voltage transistor

BF820W

FEATURES

- Low current (max. 50 mA)
- High voltage (max. 300 V).

APPLICATIONS

• Telephony and professional communication equipment.

DESCRIPTION

NPN high-voltage transistor in a SOT323 plastic package.

MARKING

TYPE NUMBER	MARKING CODE(1)
BF820W	1V*

Notes

* = p : made in Hong Kong.
 * = t : made in Malaysia.

* = W : made in China.

PINNING

PIN	DESCRIPTION				
1	base				
2	emitter				
3	collector				

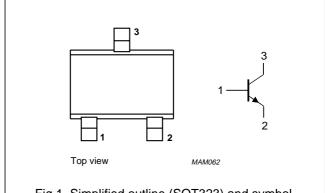


Fig.1 Simplified outline (SOT323) and symbol.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	300	V
V _{CEO}	collector-emitter voltage	open base	_	300	V
I _{CM}	peak collector current		_	100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	_	200	mW
h _{FE}	DC current gain	$I_C = 25 \text{ mA}; V_{CE} = 20 \text{ V}$	50	_	
C _{re}	feedback capacitance	$I_C = i_c = 0$; $V_{CB} = 30 \text{ V}$; $f = 1 \text{ MHz}$	_	1.6	pF
f _T	transition frequency	$I_C = 10 \text{ mA}; V_{CE} = 10 \text{ V}; f = 100 \text{ MHz}$	60	_	MHz

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	_	300	V
V _{CEO}	collector-emitter voltage	open base	_	300	V
V _{EBO}	emitter-base voltage	open collector	_	5	V
I _C	collector current (DC)		_	50	mA
I _{CM}	peak collector current		_	100	mA
I _{BM}	peak base current		_	50	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	200	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Note

1. Transistor mounted on an FR4 printed-circuit board.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	note 1	625	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

 T_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _{CBO}	collector cut-off current	I _E = 0; V _{CB} = 200 V	_	10	nA
		I _E = 0; V _{CB} = 200 V; T _j = 150 °C	_	10	μΑ
I _{EBO}	emitter cut-off current	I _C = 0; V _{EB} = 5 V	_	50	nA
h _{FE}	DC current gain	I _C = 25 mA; V _{CE} = 20 V	50	_	
V _{CEsat}	collector-emitter saturation voltage	$I_C = 30 \text{ mA}; I_B = 5 \text{ mA}; \text{ note 1}$	_	600	mV
C _{re}	feedback capacitance	$I_C = i_c = 0$; $V_{CB} = 30 \text{ V}$; $f = 1 \text{ MHz}$	_	1.6	pF
f _T	transition frequency	I _C = 10 mA; V _{CE} = 10 V; f = 100 MHz	60	_	MHz

Note

1. Pulse test: $t_p \le 300 \ \mu s; \ \delta \le 0.02.$

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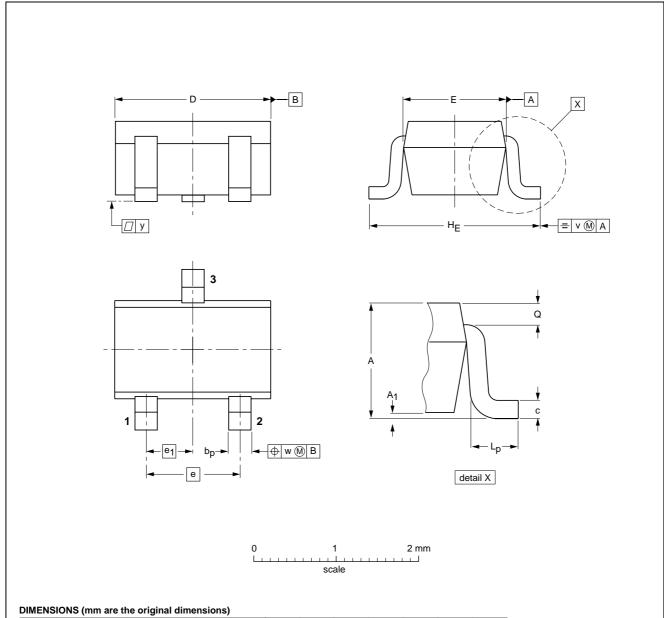
NPN high-voltage transistor

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PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT323



UNIT	Α	A ₁ max	bp	С	D	E	е	e ₁	HE	Lp	Q	v	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE		REFER	EUROPEAN ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT323			SC-70			97-02-28

Philips Semiconductors Product specification

NPN high-voltage transistor

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DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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